

ABSTRACT

A ceramic multilayer substrate is provided with a ceramic laminate (10) including a plurality of ceramic layers laminated, having a first main surface (18), and including internal circuit elements disposed in the inside; a resin layer (15) having a bonding surface (19) in contact with the first main surface (18) of the above-described ceramic laminate (10) and a mounting surface (16) opposite to the above-described bonding surface (19); external electrodes (17), each disposed on the mounting surface (16) of the above-described resin layer (15) and electrically connected to at least one of the internal circuit elements (14) of the above-described ceramic laminate (10); and a ground electrode (12), a dummy electrode, or capacitor-forming electrodes disposed at an interface between the first main surface (18) of the above-described ceramic laminate (10) and the bonding surface (19) of the above-described resin layer (15) or in the inside of the above-described resin layer (15).